

描述 / Descriptions

表面贴装肖特基整流二极管，反向电压：20~200V，正向电流：3.0A，薄型 SOD-123FL 封装。
Surface Mount Schottky Barrier Rectifier,Reverse Voltage：20 to 200 V,Forward Current：3.0A,SOD-123FL thin package。

特征 / Features

低功率损失，高效率，高正向浪涌电流能力，适用于低压、高频转换和极性保护，适用于表面贴装。无卤产品。

Low power loss,high efficiency,High forward surge current capability,For use in low voltage,high frequency inverters and polarity protection applications,For surface mounted applications.Halogen free product。

用途 / Applications

一般用途。

General purpose.

内部等效电路 / Equivalent Circuit

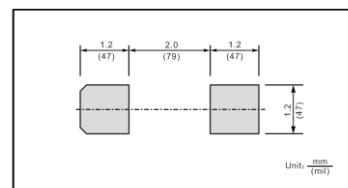


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating								单位 Unit
		DS32W	DS34W	DS36W	DS38W	DS310W	DS312W	DS315W	DS320W	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_F (AV)$	3.0								A
Peak Forward Surge current,8.3ms Single Half ine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80				70				A
Typical Junction Capacitance ¹⁾	C_i	250		160						pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	40								°C/W
Operating Junction Temperature Range	T_j	-55~+125								°C
Storage Temperature Range	T_{stg}	-55~+150								°C

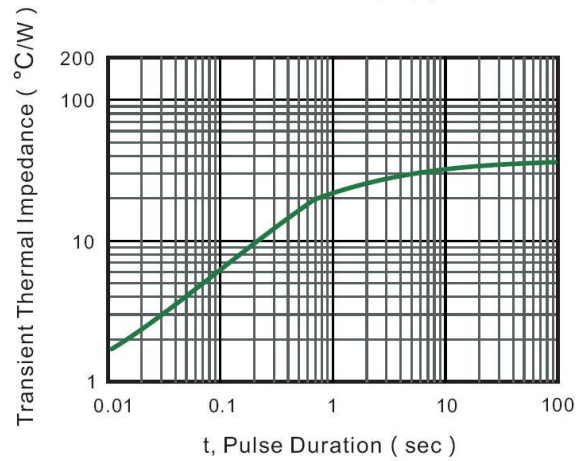
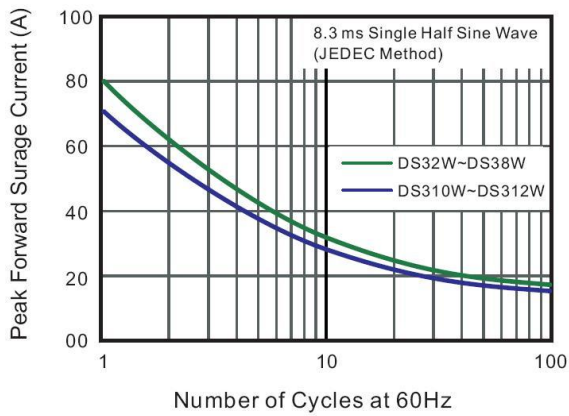
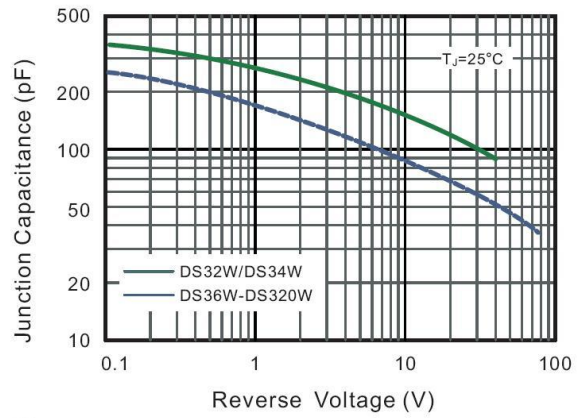
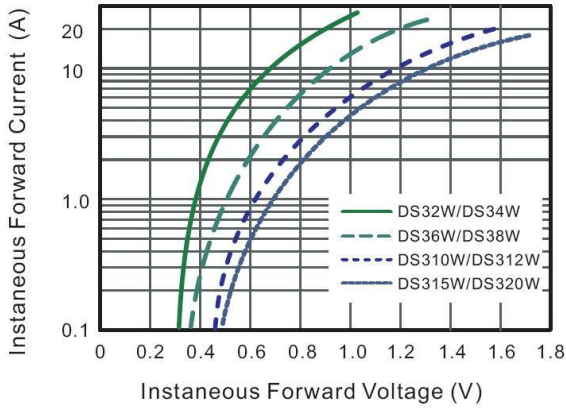
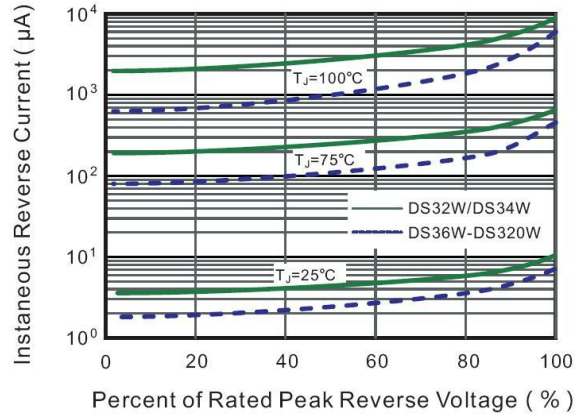
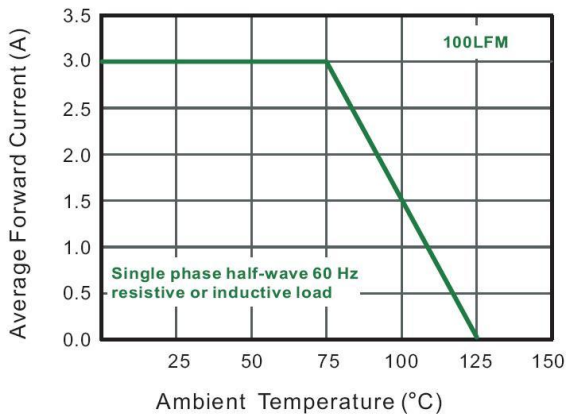
Note:

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
- 2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

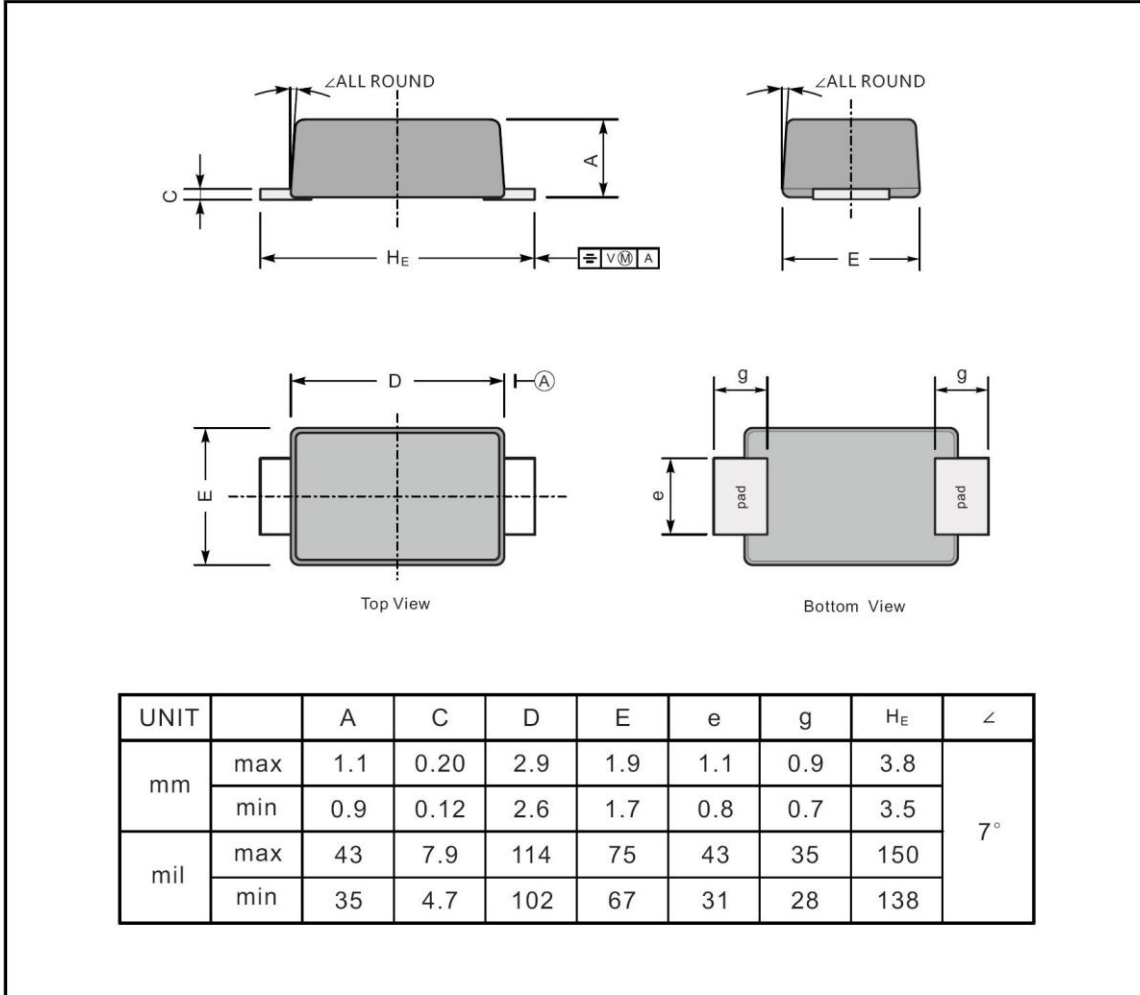
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit	
			DS32W	DS34W	DS36W	DS38W	DS310W	DS312W	DS315W		DS320W
Max Instantaneous Forward Voltage	V_F	$I_F=3.0A$	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current at Rated DC Reverse Voltage	I_R	$T_a=25^\circ C$	0.5			0.3					mA
		$T_a=100^\circ C$	10			5.0					

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SOD-123FL

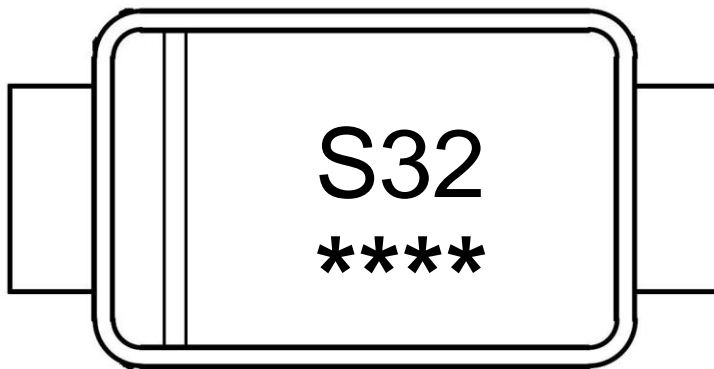


印章说明 / Marking Instructions

Marking

Type number	Marking code
DS32W	S32
DS34W	S34
DS36W	S36
DS38W	S38
DS310W	S310
DS312W	S312
DS315W	S315
DS320W	S320

印章说明 / Marking Instructions



说明：

S22： 为型号代码

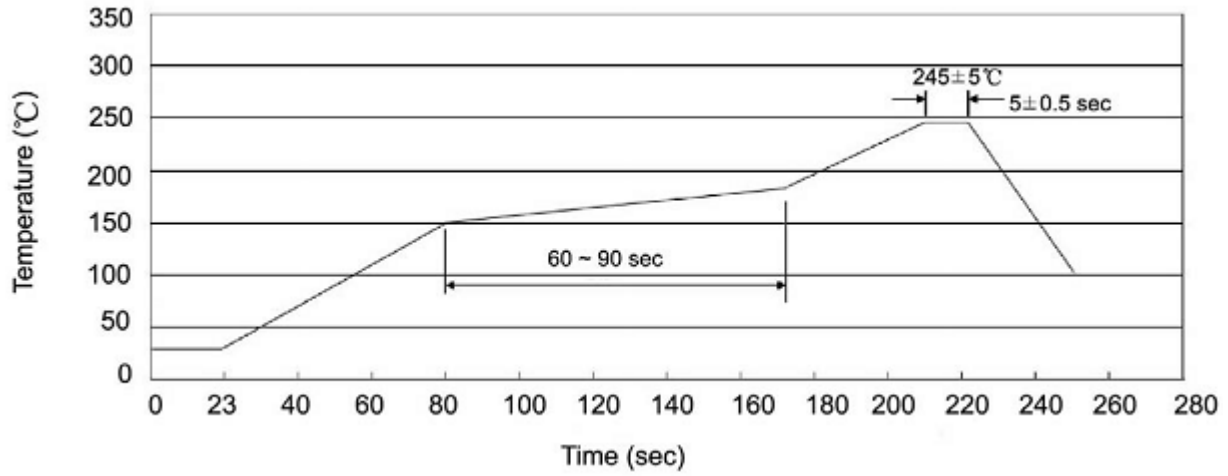
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

S22： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123FL	3000	8	24000	6	144000	7" x8	185X180X105	390X385X205

使用说明 / Notices